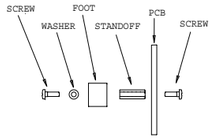
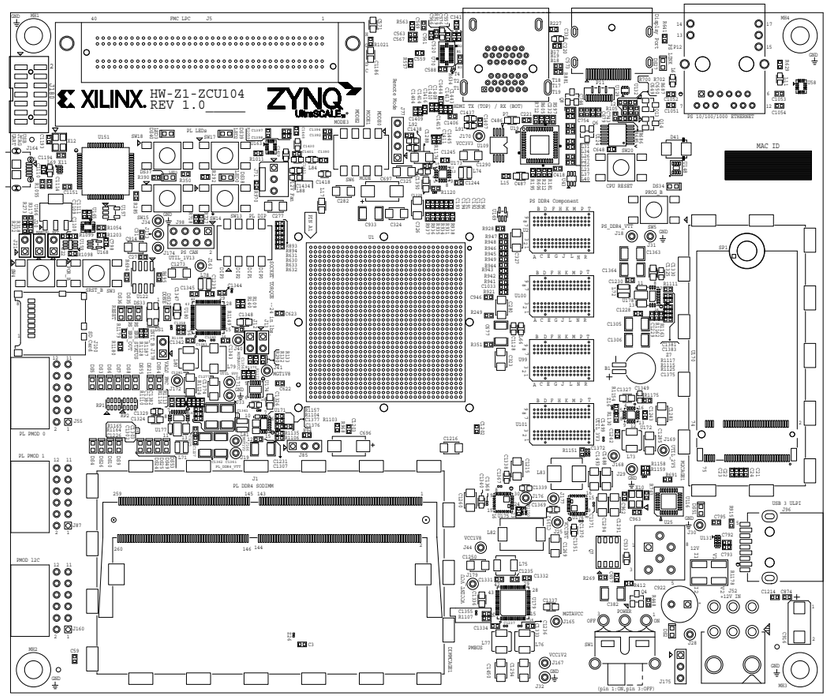
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
B	PROTOTYPE	08/30/17	
B	PROTOTYPE	08/30/17	
C	PROTOTYPE	11/27/17	
1.0	PROTOTYPE	02/10/18	
01	PROTOTYPE	02/08/18	

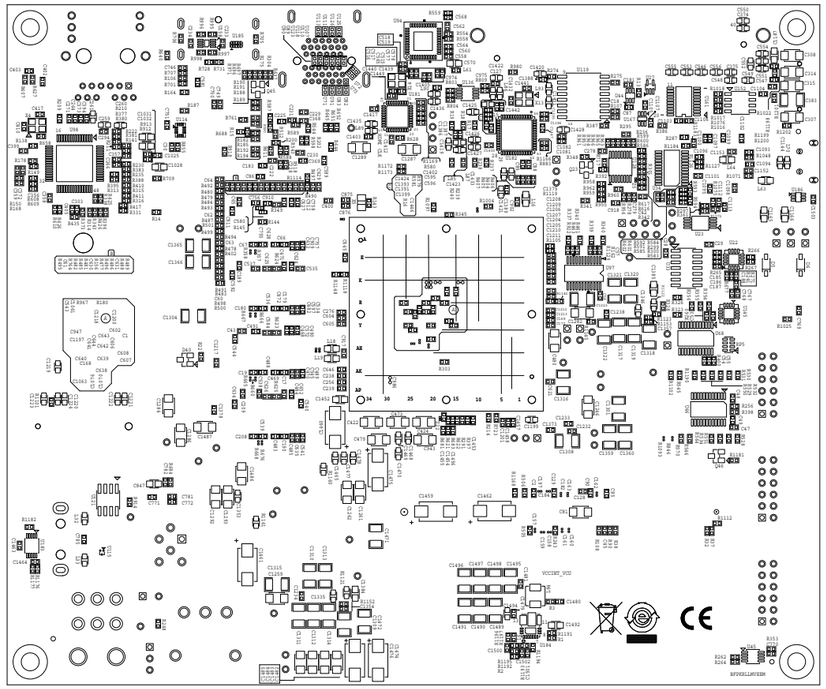
NOTES: (UNLESS OTHERWISE SPECIFIED)

1. ASSEMBLE TO MEET INSPECTION CRITERIA OF IPC-A-610, CLASS 2, CURRENT REVISION.
2. BAG AND TAG (OR MARK CONTAINER) WITH PART NUMBER.
3. REFERENCE SCHEMATIC (OR AVL) FOR BILL OF MATERIALS.
4. ASSEMBLY SHOULD BE "ROHS" AND "LEAD FREE" COMPLIANT.
5. FAB IS BOUND TO USE "SAC305" SOLDER PASTE FOR COMPONENT ASSEMBLY.
6. (a) . VERIFY THAT THE SOLDER PASTE IS NOT APPLIED TO THE BGA PADS ON THE TOPSIDE.
   (b). VERIFY THAT SOLDER PASTE IS NOT APPLIED TO THE UN-POPULATED RESISTORS AND CAPACITORS UNDERNEATH U1.
   (c). MAXIMUM PASTE MASK STENCIL THICKNESS IN THE AREA OF MAXIMUM POWER SUPPLIES (eg HPQFN_19_A DEVICIES) MUST BE 4MILS MAX.
7. SERIAL NUMBER INSTRUCTIONS:-
   " FOLLOW THE XILINX SERIAL NUMBER CONVENTION. FOR EXAMPLE KCU105 REV A IS NUMBERED 1280723A001 TO 1280723A020, REV B SHOULD START AT 1280723C001 AND END AT 1280723C075" FOR REV C IT SHOULD START AT 1280723C001
8. DATASHEET SHOULD BE FOLLOWED FOR ALL HSMF-C155 DEVICES.





VIEWED FROM TOP SIDE



VIEWED FROM BOTTOM SIDE

UNLESS OTHERWISE SPECIFIED	SIGNATURES		DATE
DIMENSIONS ARE IN INCHES	DRAWN	Rocket EMS	02-10-18
TOLERANCES ON;	CHECKED	Brian Forsse	
2 PL DECIMALS +/- .010	ENGRG	Brian Forsse	02-10-18
3 PL DECIMALS +/- .005	ISSUED		
ANGLES +			
FRACTIONS +			

XILINX.
2100 LOGIC DR.
SAN JOSE, CA 95124
HWCP - HARDWARE & CONFIGURATION PLATFORMS

ASSEMBLY DRAWING

HW-Z1-ZCU104

SIZE	FSCM NO	DWG NO	REV: 01
D		0432057	VER: 1.0
SCALE NONE		SHEET 1 OF 1	